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(54) Title: COPPER BOND WIRE AND METHOD OF MAKING THE SAME

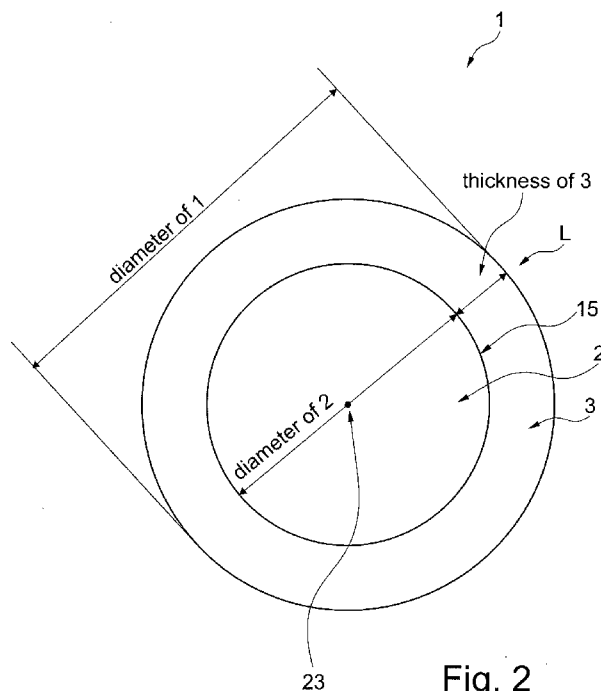


Fig. 2

(57) Abstract: The invention is related to a bonding wire, comprising a core with a surface, wherein the core comprises copper as a main component, wherein the core comprises copper as a main component, wherein an average size of crystal grains in the core is between 2.5  $\mu\text{m}$  and 30  $\mu\text{m}$ , and wherein a yield strength of the bonding wire is less than 120 MPa.



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